

Customer No.: 31561  
Docket No.: 10545-US-PA  
Application No.: 10/708,664

### AMENDMENTS

#### To The Specification

Please amend [0027] as follows:

The wetting-barrier layer 226 is disposed between the barrier layer 224 and the bump 230, for increasing the attachment of the UBM layer 220 to the bumps 230. The wetting-barrier layer 226 contains nickel and can be formed by, for example, sputtering or electroplating/chemical plating. In order to make the attachment of UBM layer 220 to the bumps 230 more reliable, the thickness of the wetting-barrier layer may larger than the adhesion layer or the barrier layer. If the wetting-barrier layer is thick enough, it may be a wetting-barrier post (not shown in FIG. 2). For example, a nickel post disposed on the barrier layer may be provided.